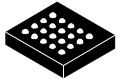


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

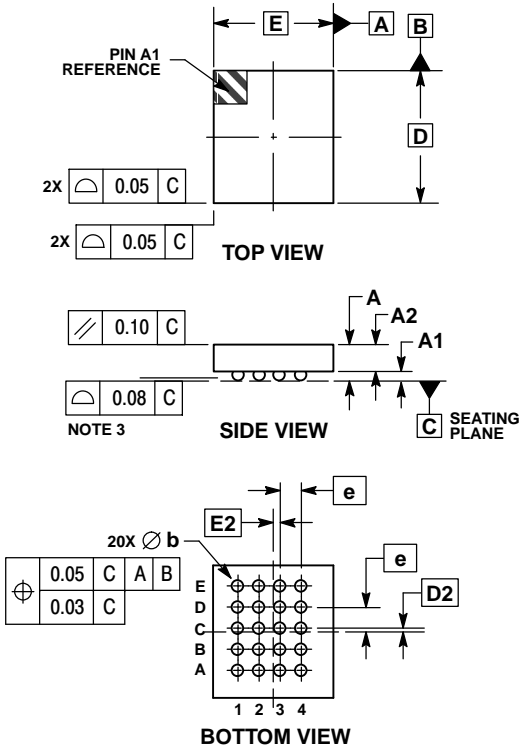
ON Semiconductor®



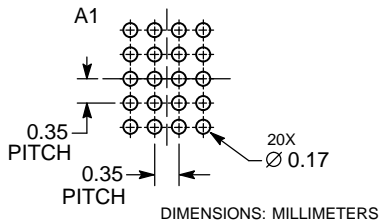
SCALE 4:1

WLCSP20 2.187x1.987  
CASE 567MZ  
ISSUE A

DATE 15 MAR 2016



### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.65
A1	0.13	0.19
A2	0.38 REF	
b	0.17	0.23
D	2.187 BSC	
D2	0.058 BSC	
E	1.987 BSC	
E2	0.112 BSC	
e	0.35 BSC	

### GENERIC MARKING DIAGRAM\*




- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WLCSP20 2.187X1.987</b>	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY C. ENRIQUEZ.	03 DEC 2015
A	CHANGED PITCH FROM 0.40MM TO 0.35MM AND ADDED DIMENSIONS D2 AND E2 FOR BUMP OFFSET FROM CENTER. REQ. BY C. ENRIQUEZ.	15 MAR 2016

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